The Runway for Sustainable Growth



2025 Investor Presentation (6548 TT)



Forward-looking Statement

Information included in this press release that are not historical in nature are "forward looking statements". CWTC cautions readers that forward looking statements are based on CWTC's reasonable knowledge and current expectations and are subject to various risks and uncertainties. Actual results may differ materially from those contained in such forward looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design win, time to market, market competition, industrial cyclicality, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations, global economy change, natural disasters, and other unexpected events which may disrupt CWTC's business and operations. Accordingly, readers should not place reliance on any forward looking statements. Except as required by law, CWTC undertakes no obligation to update any forward looking statement, whether as a result of new information, future events, or otherwise.



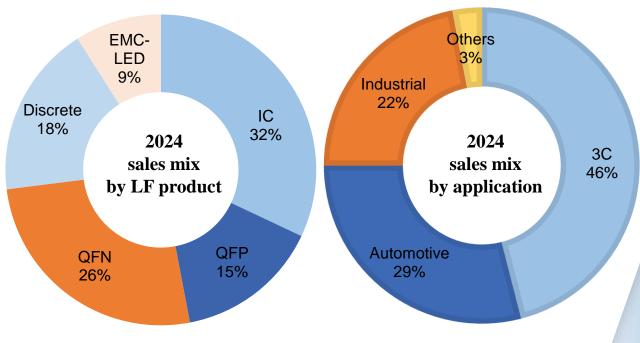
A Leading Lead Frame(LF) Solution Expert

■ Ticker: 6548 TT

■ Market Cap (Mar. 20th, 2025): US\$ 1.05bn

■ Client Scope: Outsourcing Semiconductor Assembly & Testing (OSAT),

Integrated Device Manufacturers (IDM) and IC Design



QFN: Quad-Flat No-Leads.Discrete: Small-Outline transistor,SOT

QFP: Quad Flat Package IC: SOP. TSSOP, TSOP....etc.





Why Invest In CWTC?



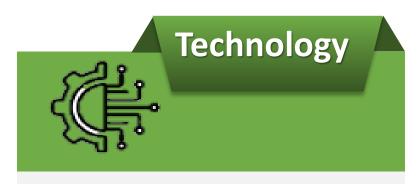
Industry leading ROE

CWTC expects to deliver an ROE in excess of 25% next five years and implements quarterly dividend payment and pay at least NT\$1.6 cash dividend per share.



Diversity in product > client & clusters

CWTC offers diversified LF products, and all factories located in 3 big semi packing clusters in Asia.



Technology

Over 30+ years experience, CWTC derives leading technology and knowhow to develop high-end LF for next generation product.

Agenda

Industry-Leading ROE

Growth Drivers

Technology & Execution Financials

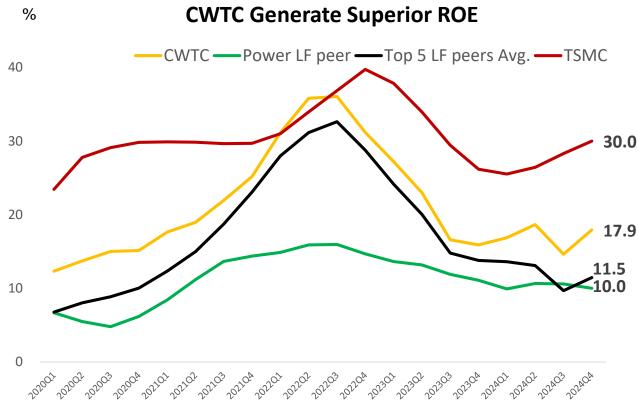




Target to Increase Market Share and Generate Superior ROE

- Among leading LF peers, CWTC targets to increase market share and become the IC LF Spec. definer.
- CWTC generated **ROE above LF industry average through cycle**.





Source: Bloomberg

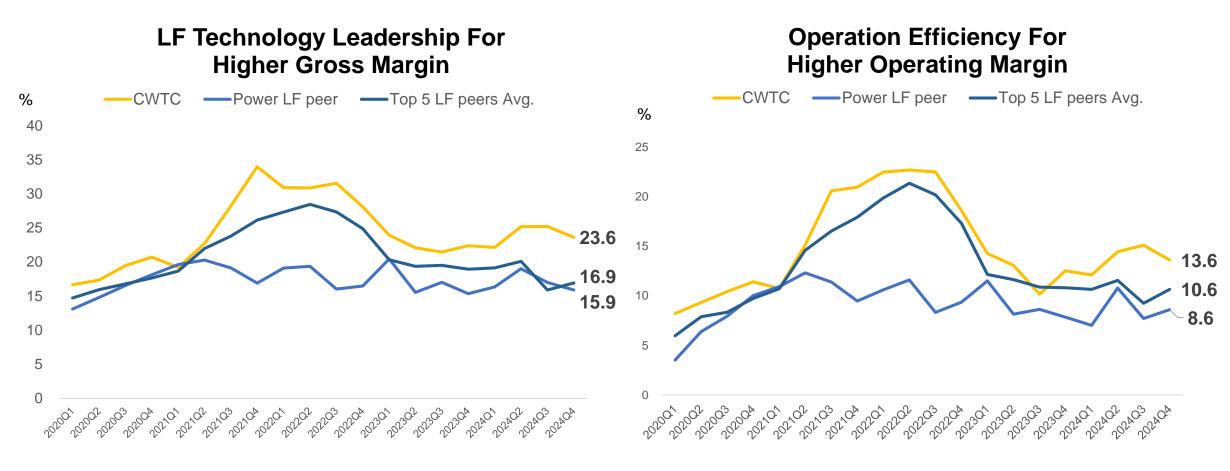
Source: Fuji Keizai 2024.

CWTC use actual production data (Ori. Data 17.4%)



We Strive to Maintain Industry Leading Profitability

Based on our LF technology leadership and operation efficiency, we expect to maintain our profitability to be above LF industry's average, leading to our superior ROE **through industry-cycle**.



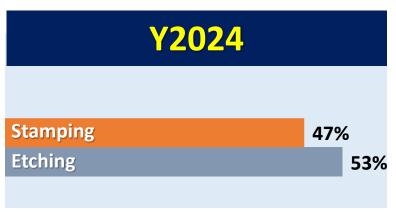
Source: Company estimates. Stock tickers: Mitsui High-tec: 6966 JP, Shinko: 6967 JP, HDS: 195870 KS, SDI: 2351 TT

Source: Bloomberg



Diversity in All Aspect





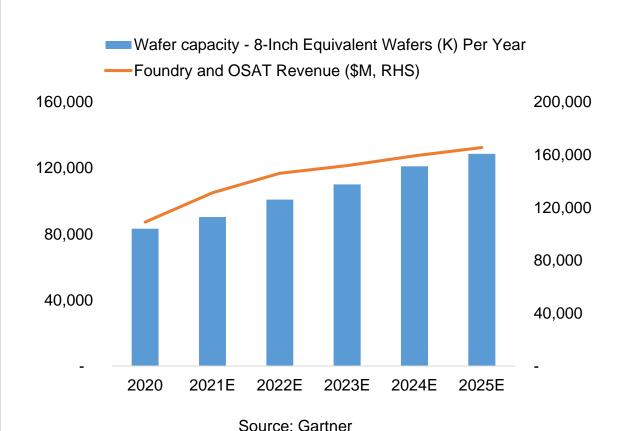




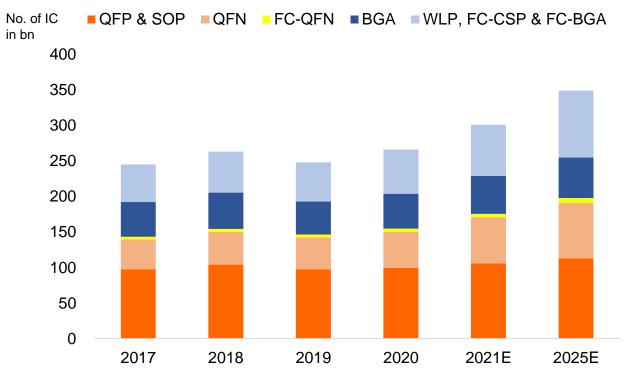


Increasing LF Demand

Wafer capacity expansion fuels industry's 9% CAGR. No. of IC will grow faster due to node migration, e.g. 65/40nm to 28/22nm.



Same with industry trend, we've seen growing QFP & QFN demand from global tier-one customers, including IDM, OSAT and IC design.



Source: Prismark



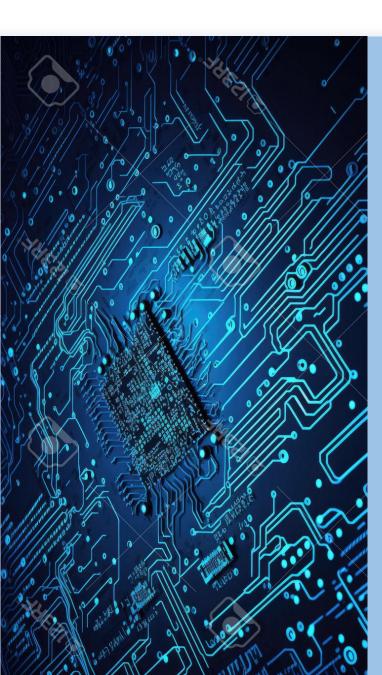
Our Multiple Applications



Various LF Spec. Requirement: No. of I/O, Form factor, Reliability, Thermal conductivity and Electrical performance



GaN IPM Module



High Efficiency



- Applied GaN Technology
- 99% inventor efficiency
- 50% reduction in power loss



Excellent Thermal Performance

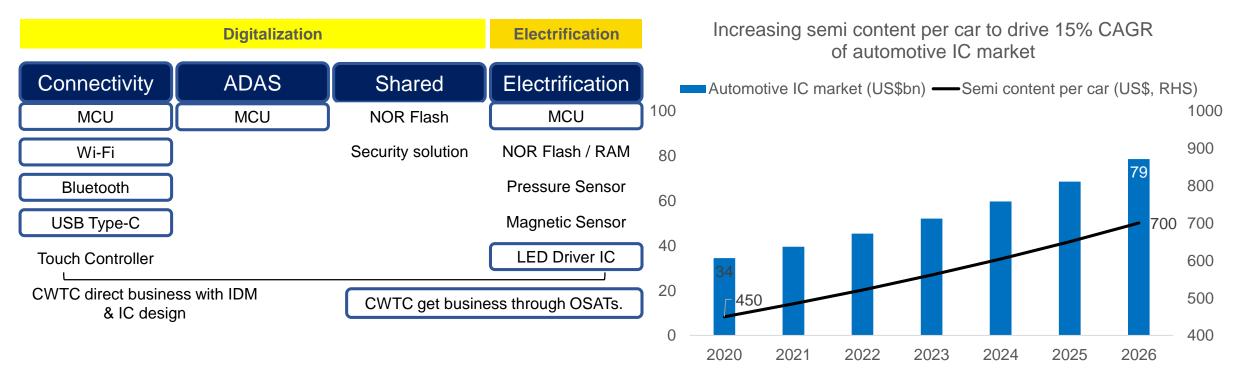
- No need for heat sink
- Reducing 50% PCB space





We Address All Vehicles Amidst the Trend of C.A.S.E

- Automotive Evolution is driven by technological developments of Connectivity, ADAS, Shared Mobility and Electrification (C.A.S.E). The C.A.S.E market would grow from US\$73bn, 2020 to US\$147bn, 2026, a 12% CAGR.
- Not just electrified vehicles (EV), the C.A.S.E evolution of automotive industry applies to all kinds of powertrains including new energy and traditional internal combust engine (ICE) vehicles.



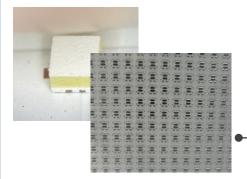
Source: Yole; WSTS; 2021 Oct. IFX day; WSTS





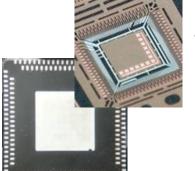


Our Leading Technology Portfolio



Pre-mold QFN

- World's leading EME-filled QFN technology
- Excellent thermal efficiency & rigidity
- Higher throughout for IC, Mini LED back-light unit, sensor and MEMS
- · Replacing entry-level organic substrate



QFN

- No. of I/O: 32-180
- Replacing SOP, co-exist with QFP and low-end BGA



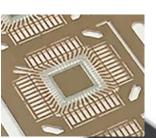
LF Technology

aQFN

- No. of I/O: **100-400**
- World's leading exclusive QFN LF
- Replacing BGA
- TW Fab started production since 4Q21



- No. of I/O: 32-256
- Flexible capacity switch between stamping and etching
- Increasing demand from OSAT & IDM customers





Industry-Leading Manufacturing Process

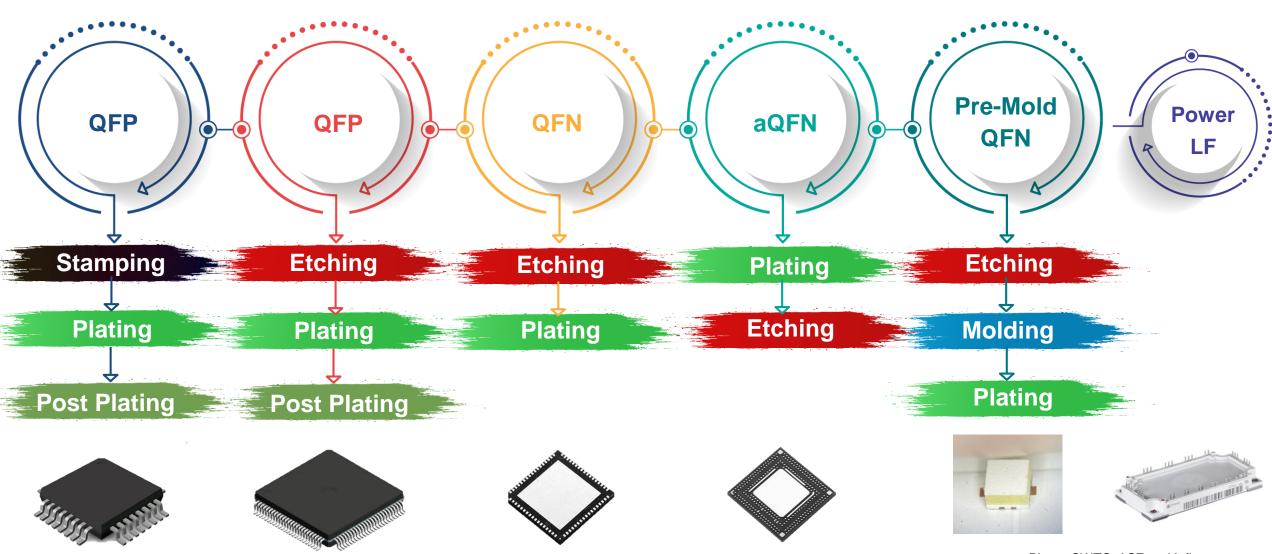


Photo: CWTC, ASE and Infineon







Operation Efficiency

- After acquiring LF business from Sumitomo Metal Mining (5713 JP) in 2018. Through its plants in Taiwan, China and Malaysia, CWTC owns industry-leading manufacturing capabilities and efficiency.
- Through leadership in efficiency and technology; early and disciplined investment, CWTC will efficiently pursue sustainable growth and gain share.



Technology Leadership





Expansion Plan in SE-Asia

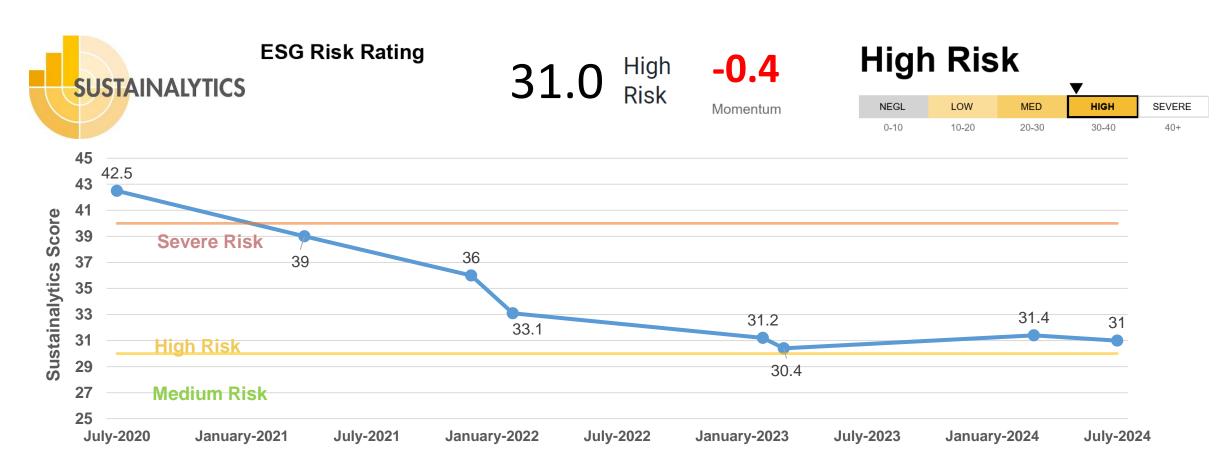


CWTC announced will invest USD100M to expand Malaysia factory! All plants located in 3 major semiconductor back-end cluster.



Our Ever-Improving ESG Performance

- Year over year improvement in our Sustainalytics ESG Score
- We expect further improvement into the medium risk category by 2025



CWTC

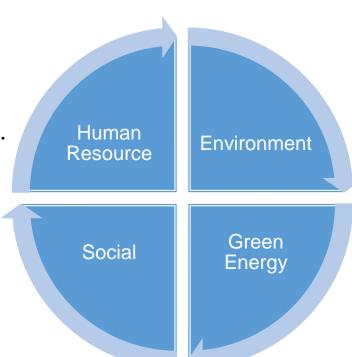
We Pursuit Our Sustainable Growth in an Eco-friendly Approach

Environment:

- Water recycling rate reached **23%** in 2024 vs. 6% in 2020.
- 4% of electricity demand at the new factory will be supplied from solar energy vs. existing factory of only 0.3%.

Social:

- We are committed to complying with the Responsible Business Alliance (RBA), the Global e-Sustainability Initiative (GeSI), and also the Responsible Minerals Initiative (RMI).
- ESOP program transferred over **1,341,000** shares to employees.
- Our new fab is expected to create more than 150 new job opportunity.
- Stringent Environmental, Health, & Safety Policy across all of our Asia factories.



CWTC 2023 ESG Report

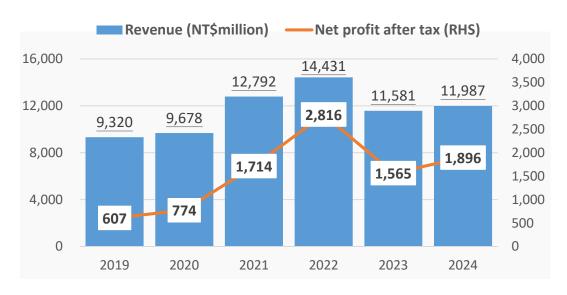


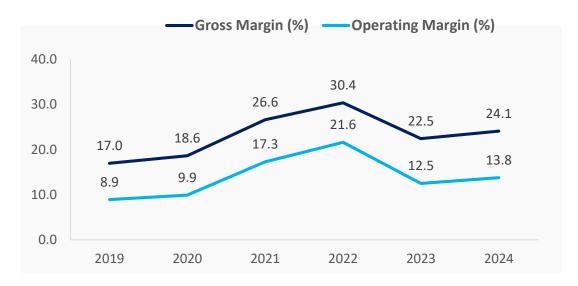


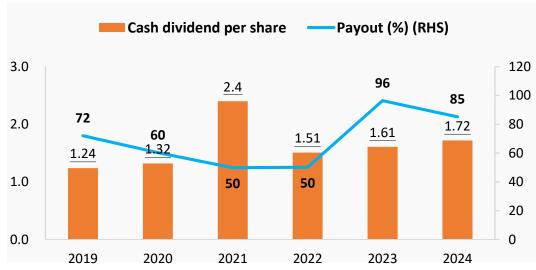


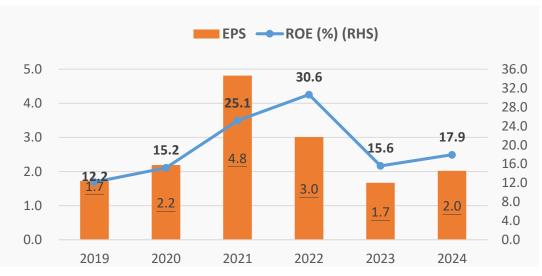


Robust Financial Performance









^{*}Since Sep. 9th, 2019, CWTC changed the par value of stock from NT\$10 to NT\$1. The EPS and dividend are one-tenth of the original numbers.

^{**}Since Sep. 5^{th,} 2022, CWTC changed the par value of stock from NT\$1 to NT\$0.4. The EPS and dividend are two-fifth of the original numbers.



2019~2024 Income Statement

NITO	2019	2020	2021	2022	2023	2024	YoY (%)					
NT\$mn							2019	2020	2021	2022	2023	2024
Revenue	9,320	9,678	12,792	14,431	11,581	11,987	-4.7	3.8	32.2	12.8	-19.7	3.5
Gross Profit	1,581	1,805	3,406	4,386	2,601	2,885	-12.3	14.2	88.7	28.8	-40.7	10.9
Operating Expenses	-748	-845	-1,195	-1,264	-1,152	-1,228	5.7	12.9	41.5	5.7	-8.8	6.6
Operating Profit	833	960	2,210	3,122	1,448	1,657	-23.9	15.3	130.2	41.2	-53.6	14.4
Pretax Income	899	966	2,249	3,634	1,970	2,361	-25.4	7.5	132.7	61.6	-45.8	19.9
Tax Expenses	-280	-176	-511	-789	-373	-430	-20.8	-37.3	190.5	54.6	-52.7	15.3
Net Income to Parent	607	774	1,714	2,816	1,565	1,896	-27.9	27.4	121.5	64.3	-44.4	21.2
Basic EPS (NT\$)	1.72	2.19	4.81	3.01	1.67	2.02						
Key Financial Ratios (%)												
Gross Margin	17.0	18.6	26.6	30.4	22.5	24.1						
Operating Expense Ratio	8.0	8.7	9.3	8.8	9.9	10.3						
Operating Margin	8.9	9.9	17.3	21.6	12.5	13.8						
Effect Tax Rate	31.2	18.2	22.7	21.7	18.9	18.2						
Net Margin	6.5	8.0	13.4	19.5	13.5	15.8						

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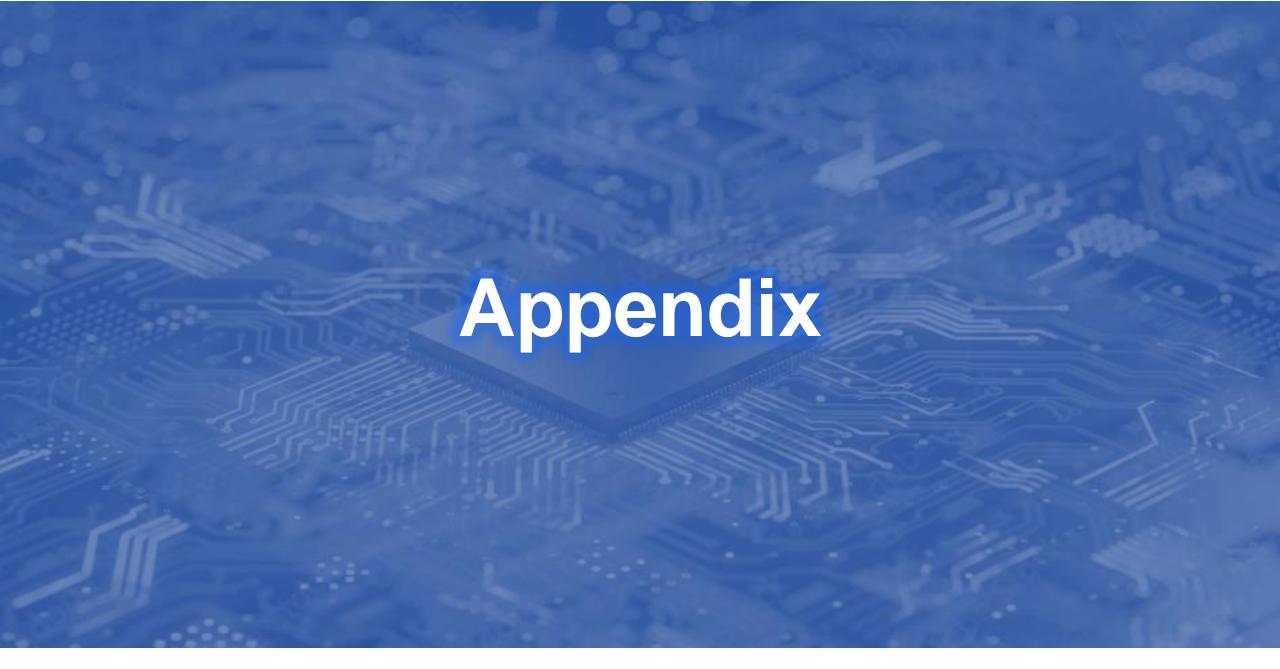


2019~2024 Balance Sheet

NITCHAN	2019	2020	2021	2022	2023	2024	YoY (%)					
NT\$mn							2019	2020	2021	2022	2023	2024
Total Assets	10,544	12,164	14,842	18,829	19,967	21,576	7.7	15.4	22.0	26.9	6.0	8.1
Cash	3,076	2,502	3,685	5,626	5,946	5,334	33.5	-18.7	47.3	52.6	5.7	-10.3
AR & NR	2,003	2,114	2,859	2,564	2,296	2,574	4.0	5.5	35.2	-10.3	-10.5	12.1
Inventories	1,296	1,437	2,196	2,456	1,931	2,539	-9.8	10.9	52.8	11.9	-21.4	31.5
Fixed Assets	2,210	2,252	2,475	3,586	3,857	3,627	-9.5	1.9	9.9	44.9	7.6	-6.0
Total Liabilities	5,558	6,738	6,430	8,655	9,634	9,884	20.4	21.2	-4.6	34.6	11.3	2.6
AP & NP	1,148	1,105	1,337	942	821	987	12.6	-3.8	21.0	-29.5	-12.9	20.2
Total Equity	4,986	5,426	8,412	10,173	10,333	11,692	-3.6	8.8	55.0	20.9	1.6	13.2
Key Financial Ratios												
A/R Turnover Days	77.9	78.2	71.7	70.0	78.6	74.2						
Inventory Turnover Days	63.5	62.5	69.7	83.4	87.9	89.7						
A/P Turnover Days	77.2	82.3	80.4	89.3	102.3	105.8						
Cash Conversion Days	64.2	58.3	61.0	64.1	64.3	58.1						
ROE (%)	12.2	15.2	25.2	31.2	15.9	17.9						
ROA (%)	6.1	7.0	12.9	16.9	8.2	9.7						

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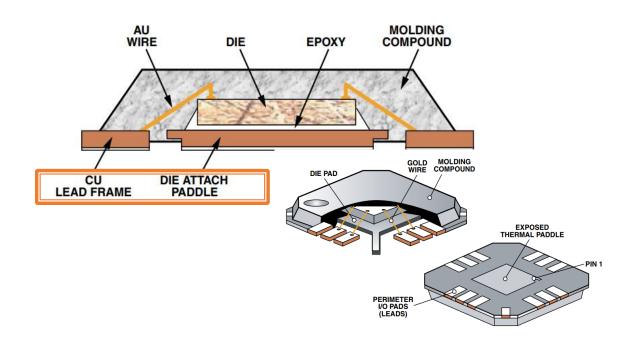


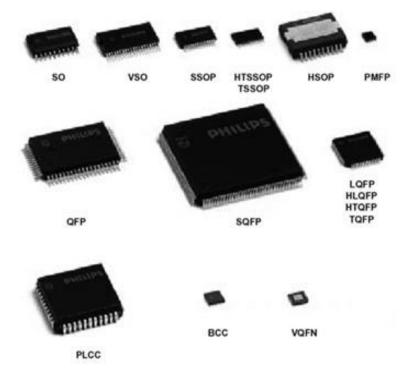




What is Lead Frame (LF)?

- LF is the **metal substrate** inside a chip package that carry signals from the die to the outside.
- LF is the interface between die and PCB, communicating signal input/output (I/O).
- By removing material from a flat plate of copper, LF are manufactured by two major processes: etching (for high I/O density with small footprint) or stamping (for less variety orders).
- There are more than dozens types of LF-based IC packages, each characteristic varying based on user requirements.



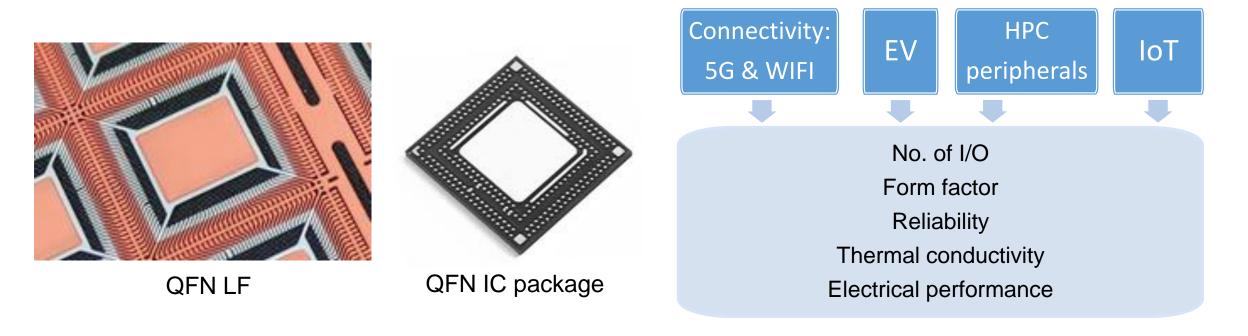


Source: Analog Device and ResearchGate



What is QFN?

- As one type of LF-based packaging, QFN is a small sized "near chip scale" plastic encapsulated IC package.
- QFN is an ideal package for IC applications where **no. of I/O**, **size**, **weight**, **thermal and electrical performance** are important.

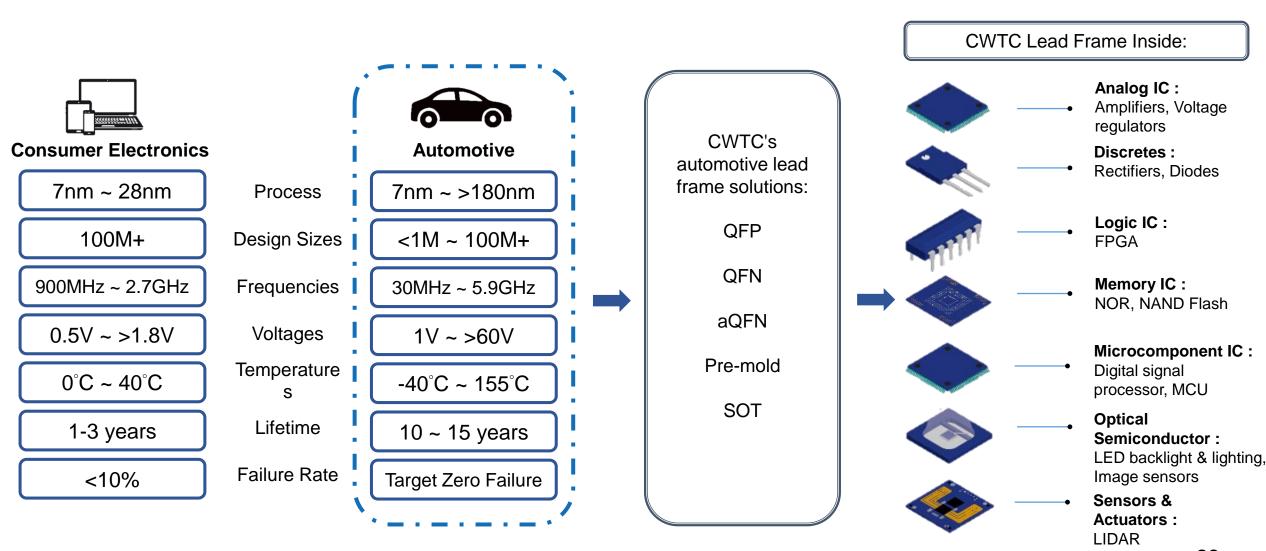


Source: CWTC and ASE



CWTC Automotive Lead Frame Inside

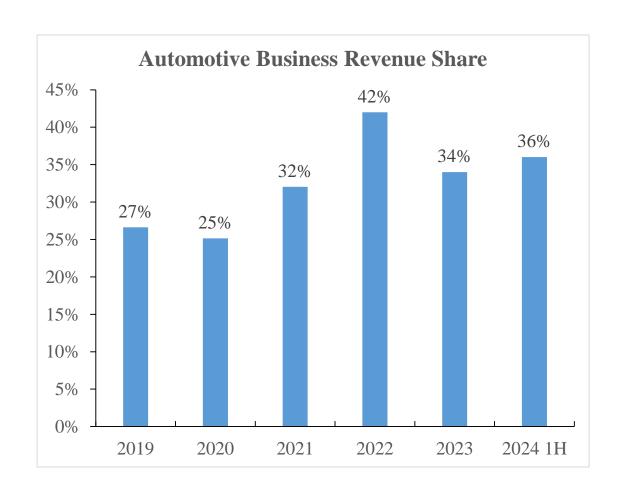
CWTC's automotive lead frame solutions to meet automotive industry specification:

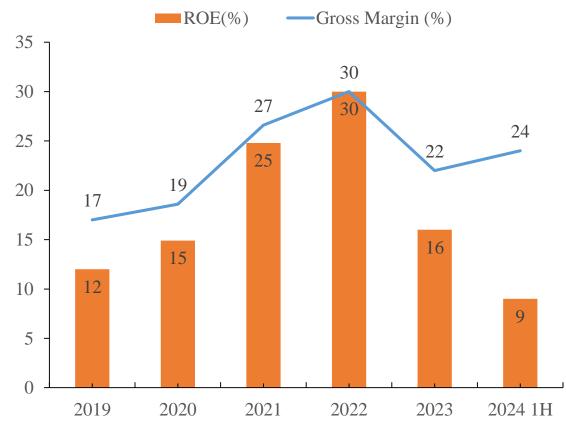




CWTC's Automotive Business

CWTC's automotive sales contribution has increased from 27% in 2019 to 36% in 2024 1H. We expect automotive LF business to continue to be one of growth drivers of our sustainable profitability.







Our Manufacturing Strength

Stamping

- Self-developed tool and mold support all QFP and SOP LF, enable to produce "CWTC-only" items.
- High flexibility to switch different products to maximize throughput

Etching

- Precise QFN half-etching technology to enhance efficiency
- Highly-automated, customized and flexible etching tools to share with QFP LF lines
- Industry leading wastewater treatment technology

Plating

- Self-developed plating mask process covering from high-end to low-end QFN
- High flexibility to switch different products.
- Self-developed photo-mask production line will be available in 2Q21

Molding

- Self-developed molding process to provide value-add to QFN LF
- Increasing pricing power for niche applications: Mini LED



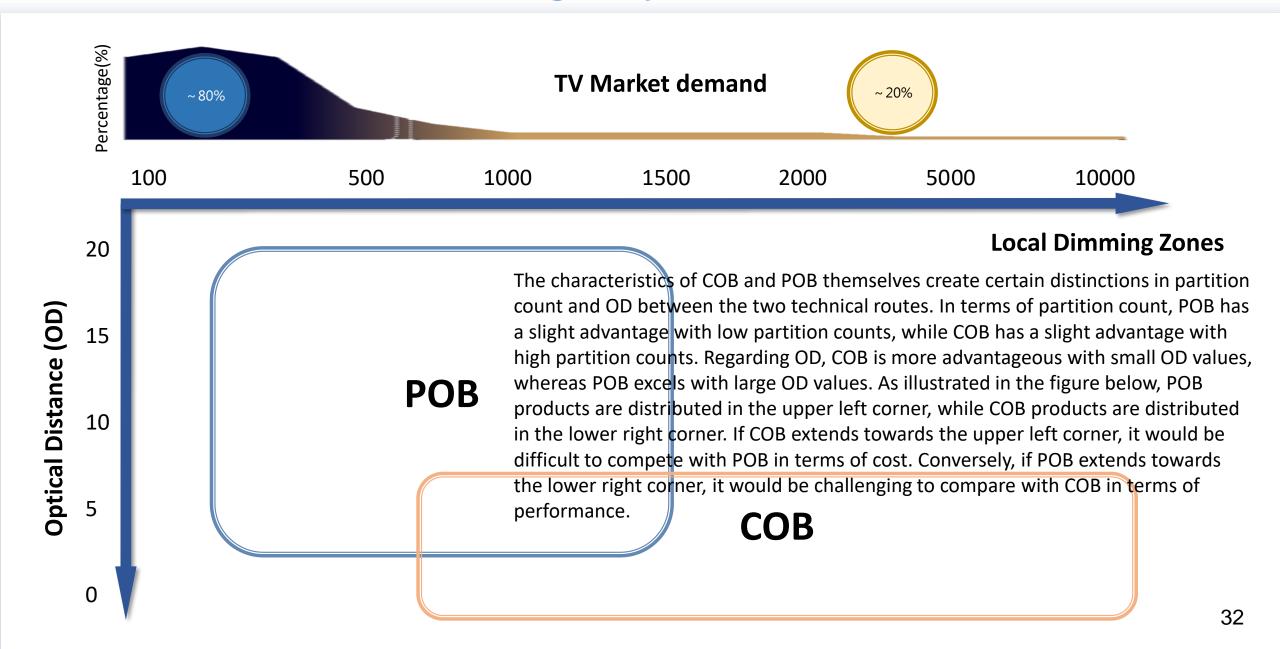
Mini LED Backlight Comparison

Mini LED Solution for Backlight			СОВ			
Package Type		CWTC EMC-2525	CWTC EMC-1515	PLCC-2016	Chip on Board	
Appearance						
Application		Monitor/ TV/ Automotive	Monitor/ TV/ Automotive Monitor/ TV/ Automotive		Monitor/ TV/ NB/Tablet	
LED Light color		Blue/White Light	Blue/White Light Blue/White Light		Blue	
LED Viewing Angel ($2\theta_{1/2}$)		≌ 170°	150°	135°	125°	
Backlight OD (Optical Distance)		2.5-5mm	2.5-5mm 3-5mm		∸ 0-5mm	
Module Thickness		Thinner	Middle	Thicker	Thinner	
Feature	Optimized view angle	날 Excellence	Workable	Difficult	Difficult	
	Hight/Pitch(H/P) Ratio	1 :4	1:2.5	1:2.3	1:1.5	
Case	LED usage in a12.3" display	≟ 384	768	1536	3456	
Comparison	Local Dimming Zones	384	384	384	384	
	Total cost	날 Low	Middle	High	Ultra-high	

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Mini LED Backlight by Different Solutions



CWTC

Glossary

- SO/SOP: Small Outline and Small Outline Package
- TSSOP: Thin Shrink Small Outline Package
- TSOP: Thin Small Outline Package
- COL: Chip-n-Lead
- QFP: Quad Flat Package
- SQFP: Small Quad Flat Package
- TQFP: Thin profile Quad Flat Package
- LQFP: Low profile Quad Flat Package
- PDIP: Plastic Dual In-line Package
- PLCC: Plastic Leaded Chip Carrier
- VSO: Very Small Outline Package
- PMFP: Plastic Micro Flat Package
- BCC: Bump Chip Carrier
- QFN: Quad Flat No-lead
- DRQFN: Dual Row Quad Flat No-Lead Package
- aQFN: advanced Quad Flat No-lead
- VQFN: Very Thin Quad Flat No-lead Package